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Hsieh et al.

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(57) **ABSTRACT**

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(60) Continuation of application No. 17/188,534, filed on Mar. 1, 2021, which is a division of application No. 16/203,919, filed on Nov. 29, 2018, now Pat. No. 10,939,551, which is a division of application No. 14/979,954, filed on Dec. 28, 2015, now Pat. No. 10,165,682.

A package includes a conductive pad, with a plurality of openings penetrating through the conductive pad. A dielectric layer encircles the conductive pad. The dielectric layer has portions filling the plurality of openings. An Under-Bump Metallurgy (UBM) includes a via portion extending into the dielectric layer to contact the conductive pad. A solder region is overlying and contacting the UBM. An integrated passive device is bonded to the UBM through the solder region.

